

TMX AT14

SAW Filter datasheet

3.0 x 3.0 mm, SMD

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SAW Bandpass Filters | Wireless Communications

Features

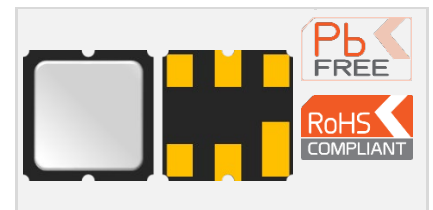
Features

- 915 MHz center frequency
- Ceramic package for Surface Mounted Technology
- Low Loss: 2.5 dB typical value within PassBand Width 902 to 928 MHz
- Maximum pulse power: 20 dBm

Applications

- Remote control - RF
- Wireless applications:
 - Home appliances
 - Security systems

3.0 x 3.0 mm



Maximum Ratings

| Parameter | Min. | Typ. | Max. | Unit |
|---|------|------|------|------|
| Storage temperature range (T_{stg}) | -40 | | 85 | °C |
| Operating temperature range (T_A) | -30 | | 80 | °C |
| DC permissive voltage | | | 5 | V |
| Maximum pulse input power | | | 20 | dBm |

Frequency and Electrical Characteristics (Reference temperature @ 25°C)

| Parameter | Min. | Typ. ¹ | Max. | Unit |
|--|-------|-------------------|------|-------|
| Center frequency (f_c) | | 915.0 | | MHz |
| Bandwidth (BW, passband width) | 26.00 | | | MHz |
| Insertion Loss (IL, 902 – 928 MHz) | | 2.5 | 3.2 | dB |
| Amplitude ripple (902 – 928 MHz) | | 0.7 | 1.6 | dB |
| Absolute Attenuation | | | | |
| D.C to 800.0 MHz | 50 | 60 | | dB |
| From 800.0 to 845.0 MHz | 50 | 55 | | dB |
| From 845.0 to 879.0 MHz | 45 | 50 | | dB |
| From 950.0 to 990.0 MHz | 25 | 30 | | dB |
| From 990.0 to 1200 MHz | 50 | 60 | | dB |
| From 1200 to 2000 MHz | 30 | 38 | | dB |
| VSWR (902 – 928 MHz) | | 1.45 | 2.0 | ppm/K |
| Source impedance ² (Single ended) | | 50 | | Ω |
| Load impedance ² (Single ended) | | 50 | | Ω |

¹ Typical values are nominal performances at room temperature

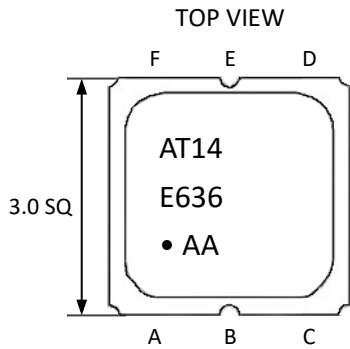
² No external matching is required

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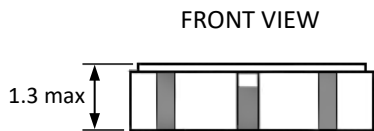
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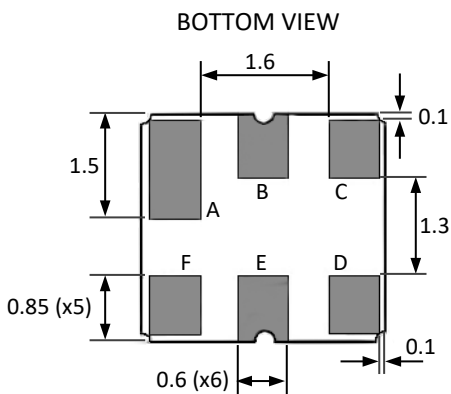
Model Outline, Pin Connection and Marking



| Marking | | Note |
|---------|------|--|
| Line 1 | AT14 | RakonXpress designation |
| Line 2 | E636 | E = Production code 6 = Year 2016 36 = Week 36 |
| Line 3 | •AA | • = Identify black dot AA = Internal code (Wafer Batch) |



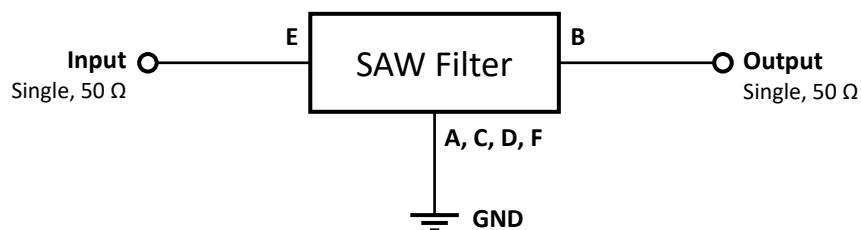
| Pin | Connections |
|------------|-------------|
| B | Output |
| E | Input |
| A, C, D, F | Ground |



Unit: mm

Test Circuit

50 Ω / 50 Ω Configuration



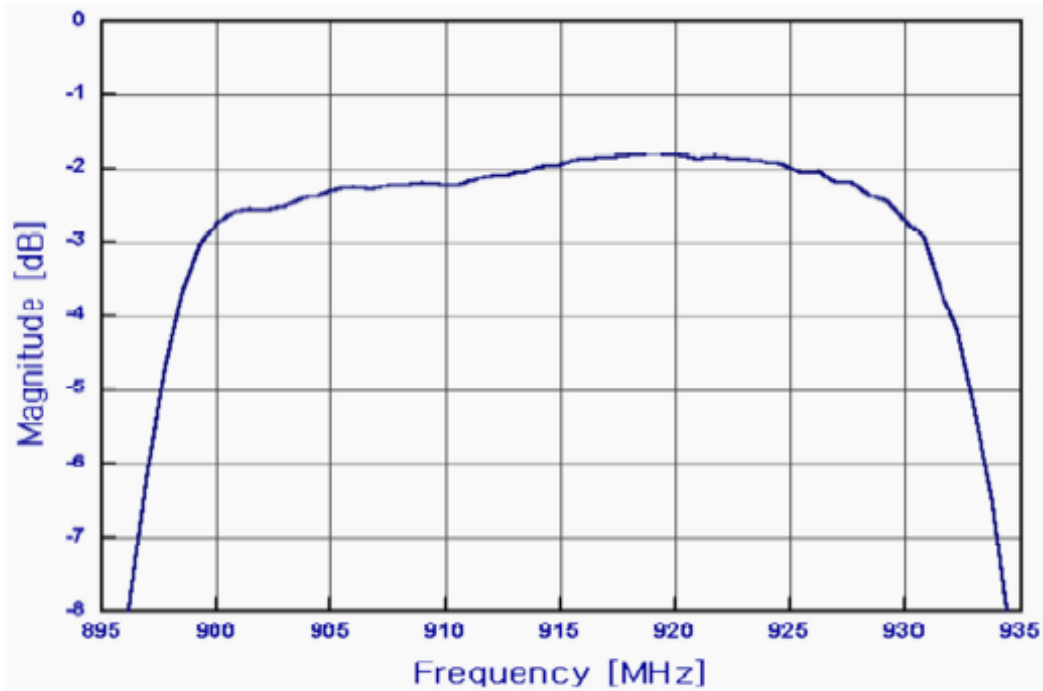
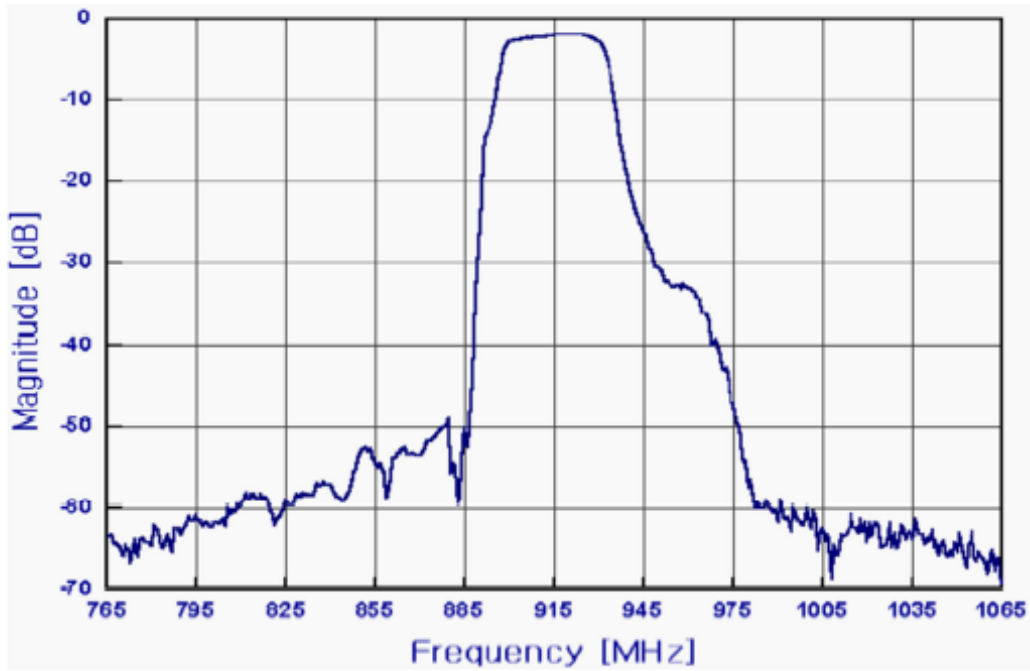
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Frequency Characteristics

TYPICAL S21 RESPONSE

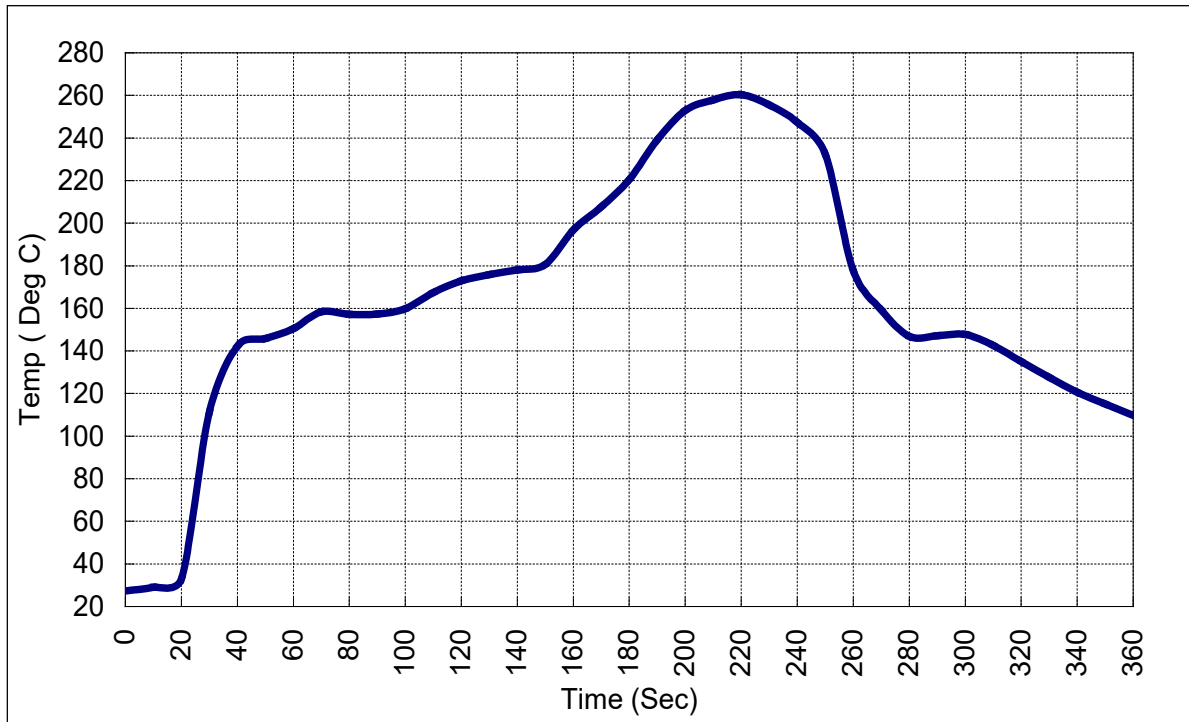


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Recommended Reflow Soldering Profile



NOTE:

- The components shall remain within the electrical specifications after it soldered on the 1mm thickness PCB board and dipped in the solder at $260 \pm 5^{\circ}\text{C}$ during 10 ± 1 seconds.
- The components shall remain within the electrical specifications after it soldered by electric iron, solder at $350 \pm 10^{\circ}\text{C}$ during 3~4 seconds. Recovery time: 2 ± 0.5 hour.
- Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- Only leads of components may be soldered. Please avoid soldering another part of the component.

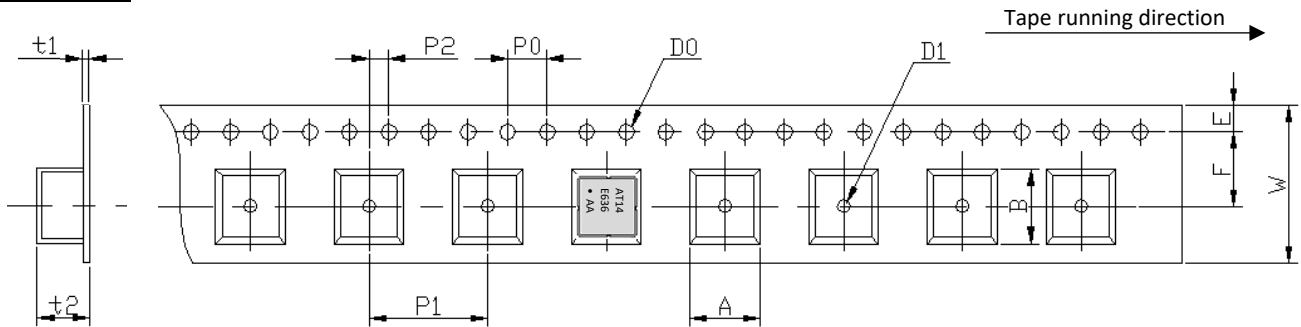
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Tape and Reel Specifications

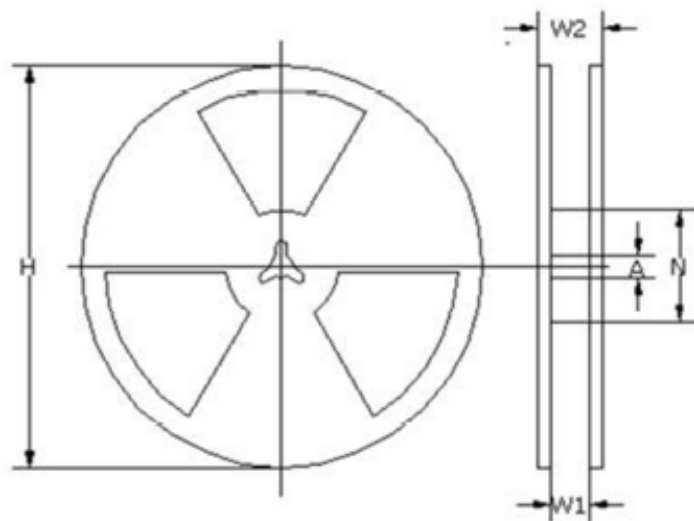
TAPE DETAILS:



| Parameter | Code | Dimension | Tolerance |
|--|----------------|-----------|-----------|
| Height of component hole | A | 3.4 | ± 0.1 |
| Width of component hole | B | 3.4 | ± 0.1 |
| Diameter of sprocket hole | D ₀ | Φ 1.5 | ± 0.1 |
| Diameter of feed hole | D ₁ | Φ 1.5 min | |
| Pitch of sprocket hole | P ₀ | 4.0 | ± 0.1 |
| Length from hole center to component center | P ₁ | 8.0 | ± 0.1 |
| Length from Pocket hole center to sprocket hole center | P ₂ | 4.0 | ± 0.1 |
| Width of carrier tape | W | 12.0 | ± 0.3 |
| Width of adhesive tape | F | 5.5 | ± 0.3 |
| Gap of hold down tape and carrier tape | E | 1.75 | ± 0.1 |
| Thickness of Embossed tape sheet | t ₁ | 0.31 max | |
| Thickness of Embossed tape | t ₂ | 1.5 max | |

REEL DETAILS:

| Code | Dimensions |
|------|-------------|
| A | Φ 13 ± 0.5 |
| N | Φ 62 ± 1.0 |
| H | Φ 330 ± 1.0 |
| W1 | 12.0 ± 1.0 |
| W2 | 16.0 ± 1.0 |



NOTE:

- Unit: mm
- Standard Packing Quantity (SPQ) is 2500 pieces/ reel

Reliability Test

| Parameter | Test condition / Description |
|---------------------|--|
| Thermal Shock | The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: TA=-40° C ±3° C, TB=85° C ±2° C, t1=t2=30min, switch time ≤3min & cycle time: 100 times, recovery time: 2h ±0.5h. |
| Temperature Storage | High Temperature Storage: The components shall remain within the electrical specifications after being kept at the 85°C ±2°C for 500 hours, recovery time: 2h ±0.5h. Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the -40°C ±3°C for 500 hours, recovery time: 2h ±0.5h. |
| Humidity test | The components shall remain within the electrical specifications after being kept at the condition of ambient temperature 60°C ±2°C, and 90~95% RH for 500 hours. |
| Drop test | The components shall remain within the electrical specifications after random free drops 10 times from height of 1.0 meter onto concrete floor, and the specimens shall meet the electrical specifications. |
| Vibration Fatigue | The components shall remain within the electrical specifications after loaded vibration at 10~55Hz, amplitude 1.5mm, X, Y, Z, direction, during 2 hours. |
| Mechanical Shock | The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s ² , duration 6ms. |
| Note | As a result of the particularity of inner structure of SAW products, the components can easily be breakdown by electrostatic shock; so it's mandatory to pay attention to ESD protect during the tests. |